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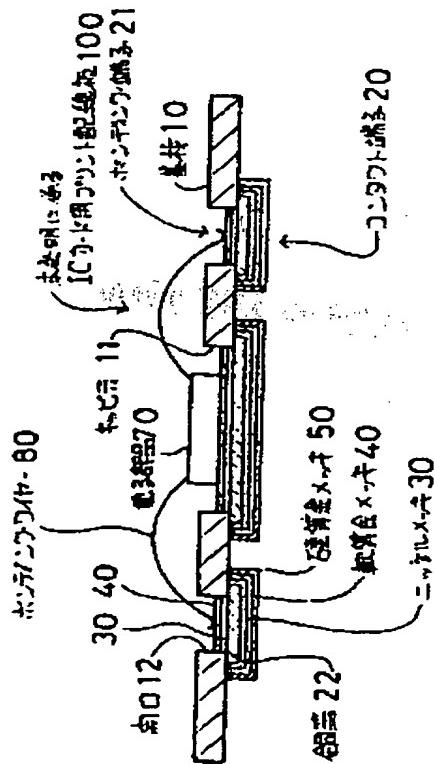
(74) Representative:

**(54) IC CARD  
PRINTED CIRCUIT  
BOARD AND  
PRODUCTION  
THEREOF**

**(57) Abstract:**

**PURPOSE:** To obtain a low-cost IC card printed circuit board superior in wear resistance and corrosion resistance and enhanced in reliability by a method wherein a soft gold plating is applied on the surface of a contact terminal, a hard gold plating is further applied thereto, and a soft gold plating is applied to the rear of the contact terminal opposed to an opening of a substrate.

**CONSTITUTION:** In an IC card printed circuit board 100, a soft gold plating 40 is on the surface of a contact terminal 20, a hard gold plating 50 is further applied thereto, and a soft gold plating 40 is applied to the rear of the contact terminal 20 opposed to an opening 12 of a substrate 10.



Because the surface of the contact terminal 20 is applied with the soft gold plating 40 and thereafter applied with the hard gold plating 50, the corrosion resistance of the surface of the contact terminal 20 is improved by a so-called layer plating effect, and the wear resistance is also ensured by the hard gold plating 50. In addition, because the rear of the contact terminal 20 is applied with the soft plating 40 at a part facing the opening 12 of the substrate 10, the connection reliability of a bonding wire 80 is improved.

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